Electronic Version
Stylesheet Version v1.1.1

PROCESS FOR MANUFACTURING PRINTED CIRCUIT BOARDS WITH PROTECTED SPACES BETWEEN TRACKS

Abstract

It comprises the steps of: a) arranging a dielectric substrate (1) with at least one conducting plate (2) joined by an adhesive (8) to at least one of its sides; b) removing areas of said plate (2) by selective chemical milling to provide conducting tracks (5) joined to the substrate (1) and separated by spaces between tracks (6); c) applying and hardening by radiation an electroinsulating filler material (7) to fill said spaces between tracks (6), covering the tracks (5); d) applying an abrasion treatment to obtain flush upper surfaces (3) of the filler material (7) and of the tracks; and e) cooling, after step c) and during step d), the printed circuit board to reduce the temperature of the filler material (7) to under its glass transition temperature.